



<b>Title of Change:</b>	NCV7518MWATXG Metal Mask Change – Addition of Redundant Vias in Digital.
<b>Proposed Changed Material First Ship Date:</b>	16 July 2020
<b>Current Material Last Order Date:</b>	Not Applicable
<b>Current Material Last Delivery Date:</b>	Not Applicable
<b>Product Category:</b>	Active components – Integrated circuits
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or < <a href="mailto:bill.fontes@onsemi.com">bill.fontes@onsemi.com</a> >
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office to place sample order or < <a href="mailto:PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> > Sample requests are to be submitted no later than 45 days after publication of this change notification.
<b>Sample Availability Date:</b>	1 July 2019 Samples are available now.  Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>PPAP Availability Date:</b>	1 July 2019 PPAP available now.
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or < <a href="mailto:youngchul.lee@onsemi.com">youngchul.lee@onsemi.com</a> >.
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> .
<b>Change Category</b>	<b>Type of Change</b>
All	Any change with impact on agreed upon contractual agreements
<b>Description and Purpose:</b>	
Metal/via mask change in order to add redundant vias to the digital core of the die.	
No design changes.	
No changes to active elements or routing.	
There are no product material changes as a result of this change.	
<b>Reason / Motivation for Change:</b>	Reduced risk of quality incidents related to via formation.  Customer Benefit: Lower incident PPM. Risk of Late Approval: Delay in receiving improved product. Quality Improvement: Yes.
<b>Anticipated impact on fit, form, function, reliability, product safety or manufacturability</b>	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.  No anticipated impacts.



<b>Sites Affected:</b>	ON Semiconductor Sites: ON Pocatello, Idaho	External Foundry/Subcon Sites: None
<b>Marking of Parts/ Traceability of Change:</b>	Affected products will be identified with date code.	
<b>Reliability Data Summary:</b>  No reliability testing needed. Characterization only.		
<b>Electrical Characteristic Summary:</b>  Electrical characteristics are not impacted.		
<b>List of Affected Part:</b>  <b>Note:</b> Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <b><u>PCN Customized Portal</u></b> .		
<b>Current Part Number</b>		<b>Qualification Vehicle</b>
NCV7518MWATXG		NCV7518MWATXG



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## Appendix A: Changed Products

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Product	Customer Part Number	New Part Number	Qualification Vehicle
NCV7518MWATXG		NCV7518MWATXG	NCV7518MWATXG